

# SN54LVT543, SN74LVT543

## 3.3-V ABT OCTAL REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS137D – MAY 1992 – REVISED JULY 1995

- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Support Unregulated Battery Operation Down to 2.7 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $< 0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ( $C = 200$  pF,  $R = 0$ )
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (JT) DIPs

### description

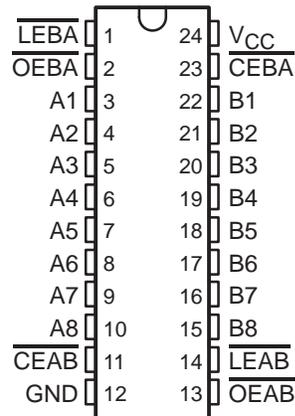
These octal transceivers are designed specifically for low-voltage (3.3-V)  $V_{CC}$  operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVT543 contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable ( $\overline{LEAB}$  or  $\overline{LEBA}$ ) and output-enable ( $\overline{OEAB}$  or  $\overline{OEBA}$ ) inputs are provided for each register to permit independent control in either direction of data flow.

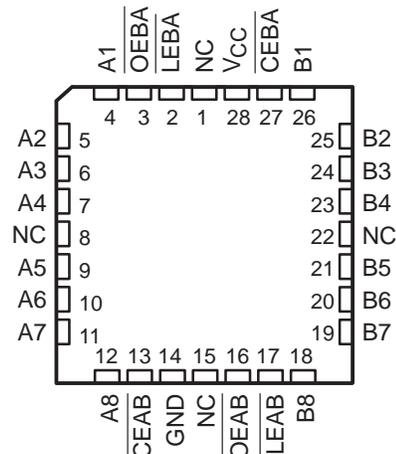
The A-to-B enable ( $\overline{CEAB}$ ) input must be low in order to enter data from A or to output data from B. If  $\overline{CEAB}$  is low and  $\overline{LEAB}$  is low, the A-to-B latches are transparent; a subsequent low-to-high transition of  $\overline{LEAB}$  puts the A latches in the storage mode. With  $\overline{CEAB}$  and  $\overline{OEAB}$  both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$  inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

SN54LVT543 . . . JT PACKAGE  
SN74LVT543 . . . DB, DW, OR PW PACKAGE  
(TOP VIEW)



SN54LVT543 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection



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**TEXAS  
INSTRUMENTS**

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# SN54LVT543, SN74LVT543

## 3.3-V ABT OCTAL REGISTERED TRANSCEIVERS

### WITH 3-STATE OUTPUTS

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#### description (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT543 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVT543 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74LVT543 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

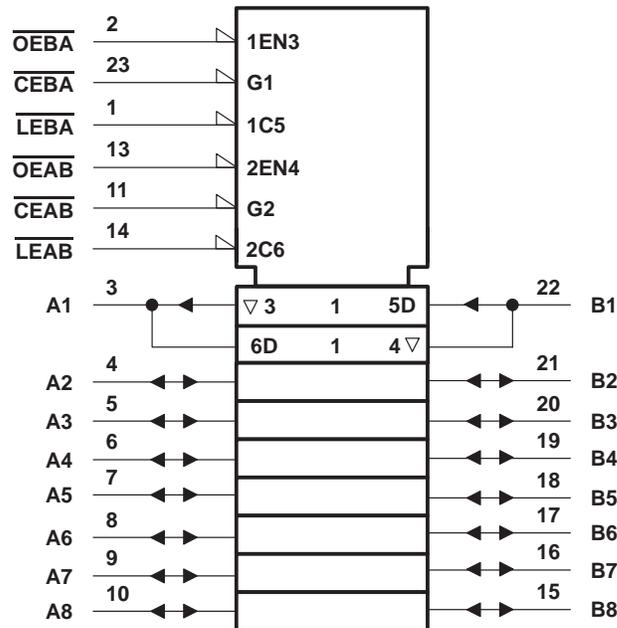
FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	$B_0^{\ddagger}$
L	L	L	L	L
L	L	L	H	H

† A-to-B data flow is shown; B-to-A flow control is the same except that it uses  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$ .

‡ Output level before the indicated steady-state input conditions were established

#### logic symbols§

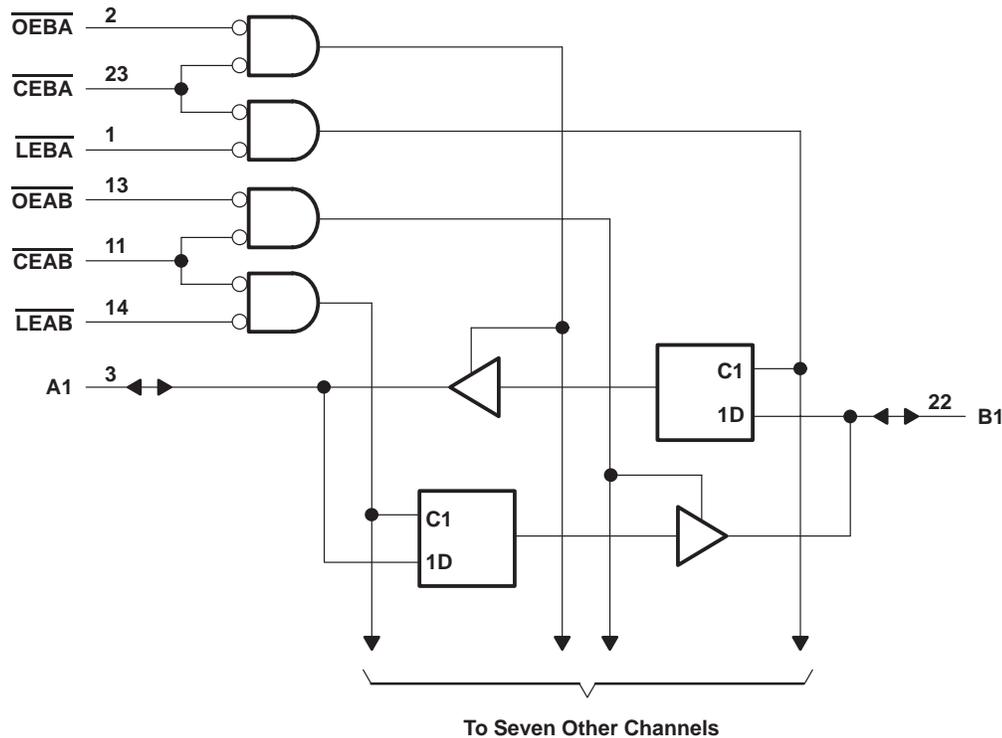


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and PW packages.

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**logic diagram (positive logic)**



Pin numbers shown are for the DB, DW, JT, and PW packages.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	-0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, $V_O$ (see Note 1) .....	-0.5 V to 7 V
Current into any output in the low state, $I_O$ : SN54LVT543 .....	96 mA
SN74LVT543 .....	128 mA
Current into any output in the high state, $I_O$ (see Note 2): SN54LVT543 .....	48 mA
SN74LVT543 .....	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	-50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	-50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DB package .....	0.65 W
DW package .....	1.7 W
PW package .....	0.7 W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
  3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



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**recommended operating conditions (see Note 4)**

		SN54LVT543		SN74LVT543		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2.7	3.6	2.7	3.6	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage		0.8		0.8	V
V <sub>I</sub>	Input voltage		5.5		5.5	V
I <sub>OH</sub>	High-level output current		-24		-32	mA
I <sub>OL</sub>	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54LVT543		SN74LVT543		UNIT	
			MIN	TYP†	MAX	MIN		TYP†
$V_{IK}$	$V_{CC} = 2.7\text{ V}$ , $I_I = -18\text{ mA}$		-1.2		-1.2		V	
$V_{OH}$	$V_{CC} = \text{MIN to MAX}^\ddagger$ , $I_{OH} = -100\ \mu\text{A}$		$V_{CC}-0.2$		$V_{CC}-0.2$		V	
	$V_{CC} = 2.7\text{ V}$ , $I_{OH} = -8\text{ mA}$		2.4		2.4			
	$V_{CC} = 3\text{ V}$	$I_{OH} = -24\text{ mA}$	2		2			
$I_{OH} = -32\text{ mA}$								
$V_{OL}$	$V_{CC} = 2.7\text{ V}$	$I_{OL} = 100\ \mu\text{A}$	0.2		0.2		V	
		$I_{OL} = 24\text{ mA}$	0.5		0.5			
	$V_{CC} = 3\text{ V}$	$I_{OL} = 16\text{ mA}$	0.4		0.4			
		$I_{OL} = 32\text{ mA}$	0.5		0.5			
		$I_{OL} = 48\text{ mA}$	0.55					
		$I_{OL} = 64\text{ mA}$			0.55			
$I_I$	$V_{CC} = 3.6\text{ V}$ , $V_I = V_{CC}$ or GND		Control inputs		$\pm 1$		$\mu\text{A}$	
	$V_{CC} = 0$ or $\text{MAX}^\ddagger$ , $V_I = 5.5\text{ V}$		A or B ports§		10			
	$V_{CC} = 3.6\text{ V}$	$V_I = 5.5\text{ V}$	20		20			
		$V_I = V_{CC}$	5		5			
		$V_I = 0$	-10		-10			
$I_{off}$	$V_{CC} = 0$ , $V_I$ or $V_O = 0$ to $4.5\text{ V}$				$\pm 100$		$\mu\text{A}$	
$I_{I(\text{hold})}$	$V_{CC} = 3\text{ V}$	$V_I = 0.8\text{ V}$	75		75		$\mu\text{A}$	
		$V_I = 2\text{ V}$	-75		-75			
$I_{OZH}$	$V_{CC} = 3.6\text{ V}$ , $V_O = 3\text{ V}$		1		1		$\mu\text{A}$	
$I_{OZL}$	$V_{CC} = 3.6\text{ V}$ , $V_O = 0.5\text{ V}$		-1		-1		$\mu\text{A}$	
$I_{CC}$	$V_{CC} = 3.6\text{ V}$ , $V_I = V_{CC}$ or GND	$I_O = 0$ ,	Outputs high	0.13	0.19	0.13	0.19	mA
			Outputs low	8.8	12	8.8	12	
			Outputs disabled	0.13	0.19	0.13	0.19	
$\Delta I_{CC}^\parallel$	$V_{CC} = 3\text{ V to }3.6\text{ V}$ , One input at $V_{CC} - 0.6\text{ V}$ , Other inputs at $V_{CC}$ or GND		0.2		0.2		mA	
$C_i$	$V_I = 3\text{ V}$ or 0		4.5		4.5		pF	
$C_{io}$	$V_O = 3\text{ V}$ or 0		11		11		pF	

† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

§ Unused terminals at  $V_{CC}$  or GND

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

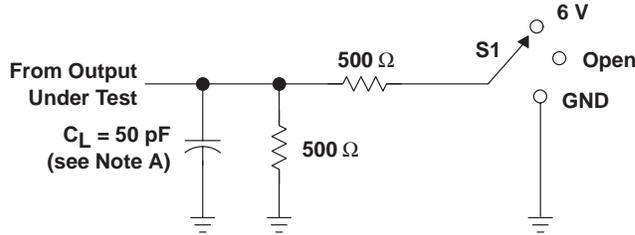
			SN54LVT543				SN74LVT543				UNIT
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_W$	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low		3.3		3.3		3.3		3.3	ns	
$t_{SU}$	Setup time	A or B before $\overline{LEAB}$ or $\overline{LEBA}\uparrow$	Data high		0		0		0		ns
			Data low		0.8		1.1		0.8		
		A or B before $\overline{CEAB}$ or $\overline{CEBA}\uparrow$	Data high		0		0		0		
			Data low		0.9		1.2		0.9		
$t_H$	Hold time	A or B after $\overline{LEAB}$ or $\overline{LEBA}\uparrow$			1.7		1.7		1.7		ns
		A or B after $\overline{CEAB}$ or $\overline{CEBA}\uparrow$			1.8		1.8		1.8		

switching characteristics over recommended operating free-air temperature range,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT543				SN74LVT543				UNIT	
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
$t_{PLH}$	A or B	B or A	1	4.9	5.7		1	2.9	4.7	5.5		ns
$t_{PHL}$			1	4.8	6		1	3.3	4.6	5.8		
$t_{PLH}$	$\overline{LE}$	A or B	1	6.1	7.5		1	4	5.9	7.3		ns
$t_{PHL}$			1	5.9	7.5		1	4.1	5.7	7.3		
$t_{PZH}$	$\overline{OE}$	A or B	1	6	7.8		1	4.1	5.8	7.6		ns
$t_{PZL}$			1.1	6.6	8.4		1.1	4.5	6.4	8.2		
$t_{PHZ}$	$\overline{OE}$	A or B	2.4	6.7	7.3		2.4	4.8	6.5	7.1		ns
$t_{PLZ}$			2	6	6.1		2	4	5.8	5.9		
$t_{PZH}$	$\overline{CE}$	A or B	1	6.2	7.8		1	4.2	6	7.6		ns
$t_{PZL}$			1.4	6.9	8.5		1.4	4.7	6.7	8.3		
$t_{PHZ}$	$\overline{CE}$	A or B	2.3	6.6	7.3		2.3	4.7	6.4	7.1		ns
$t_{PLZ}$			2	5.6	5.8		2	3.8	5.4	5.6		

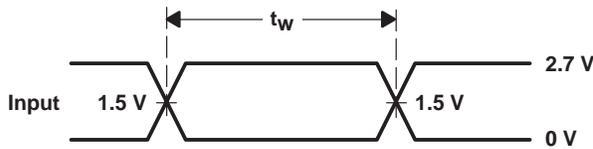
† All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

PARAMETER MEASUREMENT INFORMATION

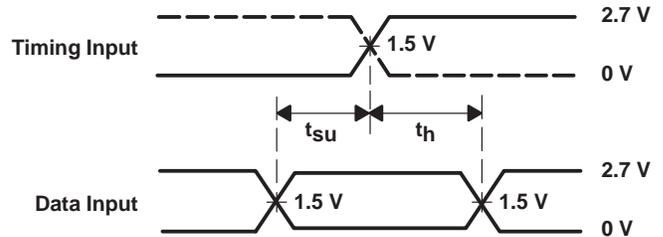


TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND

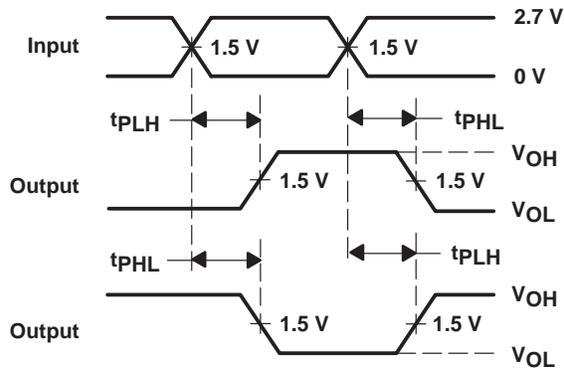
LOAD CIRCUIT FOR OUTPUTS



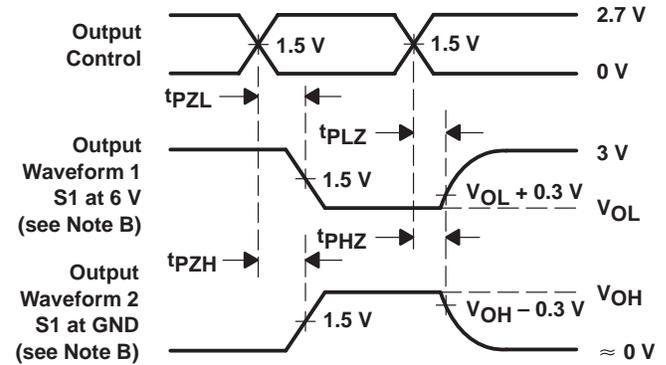
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.  
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT543DW	NRND	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT543	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

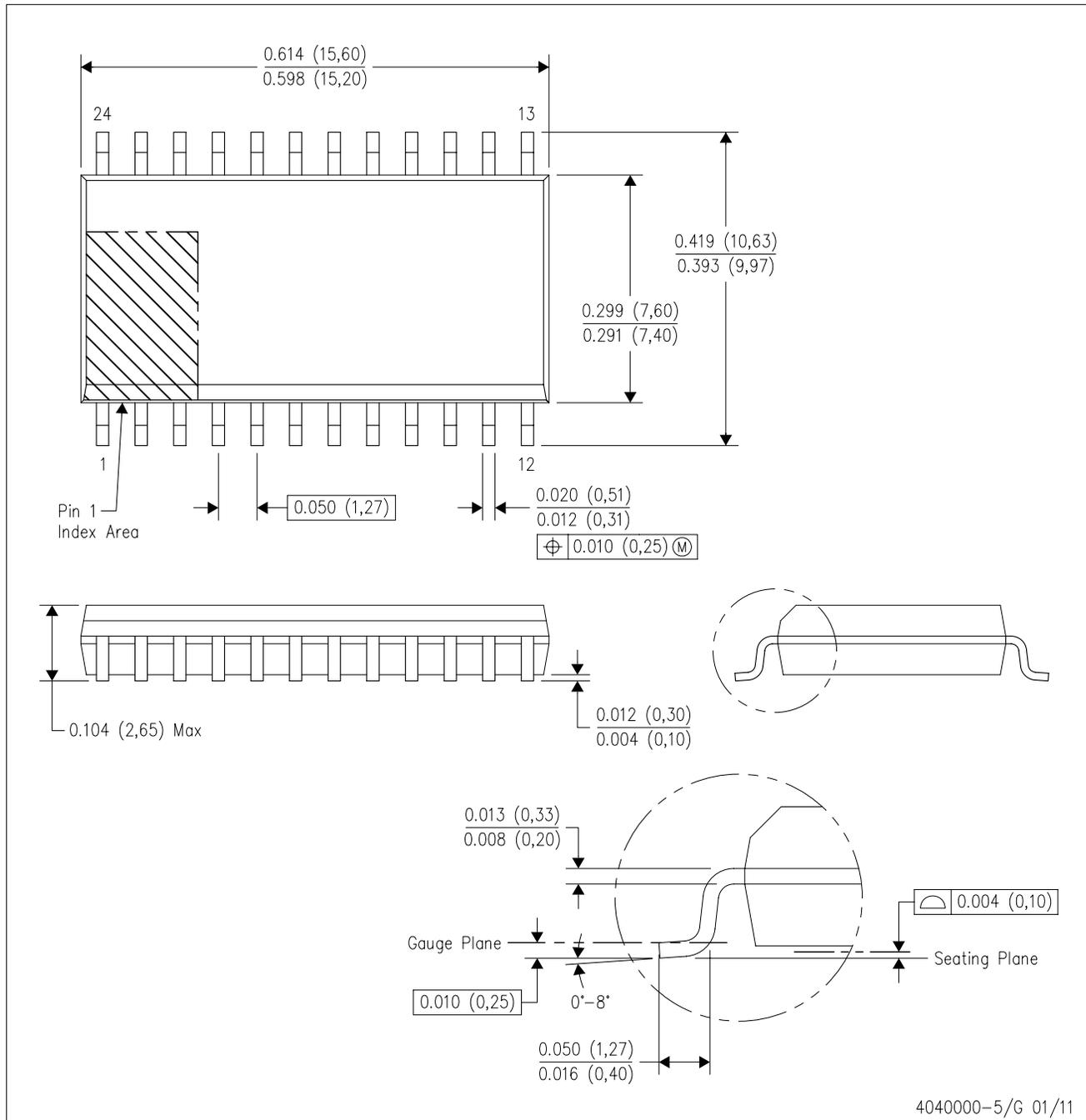
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DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

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